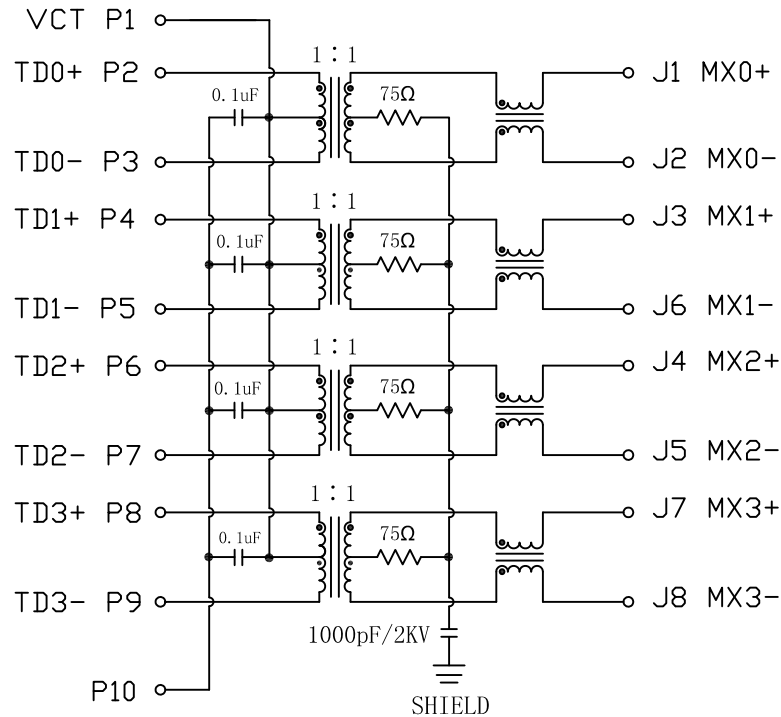


Schematic:

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		2011/08/17	

INPUT

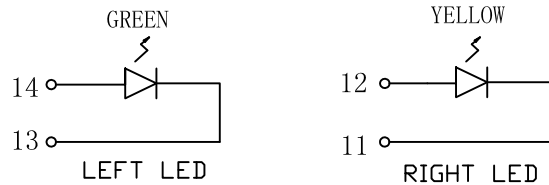
RJ45



Electrical Specifications:

TEST NOTES (25 ± 5°C)

- TR: (100KHz, 0.1V):
TX=1 : 1 ± 2% RX=1 : 1 ± 2%
- LX (100KHz, 100mV, 8mA, DC Bias):
350uH MIN
- HIPOT:
1500VAC FOR 60 SECONDS
- INSERTION LOSS:
-1.0dB MAX @ 1.0MHz TO 100MHz
- RETURN LOSS:
-18dB MIN @ 1MHz TO 30MHz
-16dB MIN @ 30MHz TO 60MHz
-12dB MIN @ 60MHz TO 80MHz
- CROSS TALK:
-40dB MIN @ 1MHz TO 10MHz
-35dB MIN @ 32MHz TO 60MHz
-30dB MIN @ 60MHz TO 100MHz
- COMMON TO COMMON MODE REJECTION:
-30dB MIN @ 1MHz TO 50MHz
-20dB MIN @ 50MHz TO 150MHz
- OPERATING TEMPERATURE: -40°C TO +85°C.



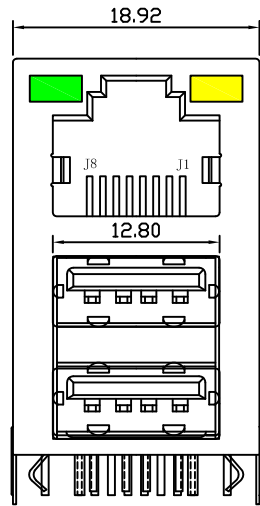
Emitting Color	λ p(nm)	VF@IF=20mA	IR @VR=5V
Green	570	1.8~2.6V	10 μ A max
Yellow	585	1.8~2.6V	10 μ A max



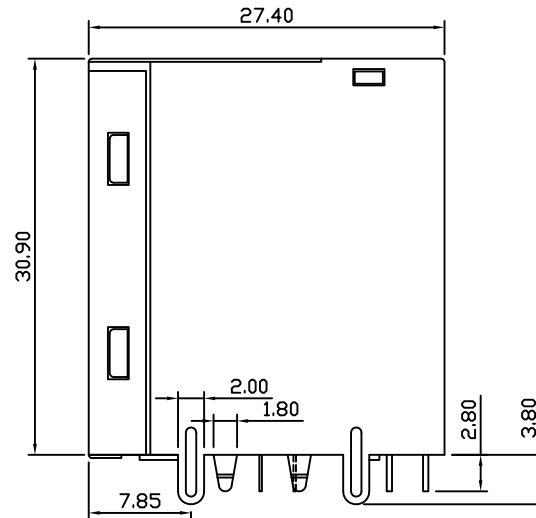
X:X	±0.30	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED
X:XX	±0.20	CHKD:	
X:XXX	±0.10	DR: TOM	Title: RJ45 10/100/1000BASE-TX JACK/ Dual USB Combo
ANGLES	±1°	UNIT: mm	PART NO.: LPJU5601BHNL
	SCALE: 2/1	SHEET: 1/2	REV: A
			DWG NO.: LP11081704

Mechanical :

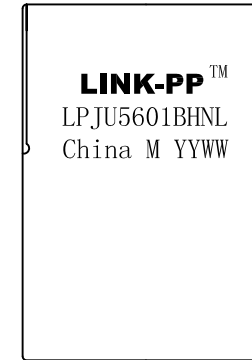
REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		2011/08/17	



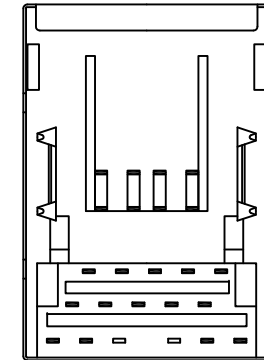
Front Side View



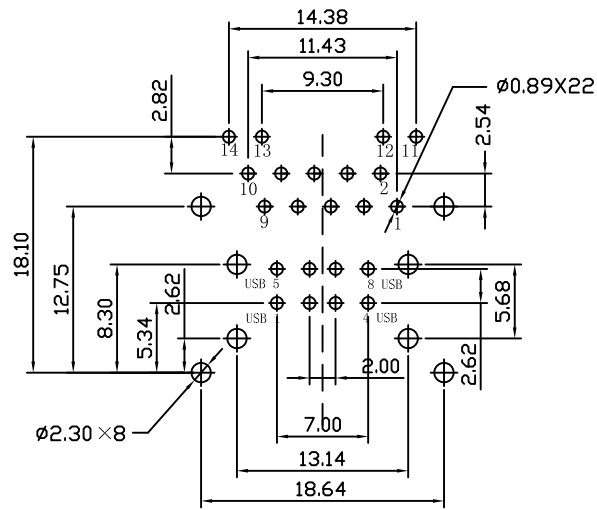
Left Side View



Top Side View



Bottom Side View



Suggested PCB Layout(Top View)



NOTES:

1. Designed to support application, such as SOHO (ADSL modems), LAN-on-Motherboard (LOM), hub and Switches.
2. Meets IEEE 802.3 specification
3. Connector Materials:
 Housing Material: Thermoplastic PBT+30%G.F UL94V-0
 Contact Material: Phosphor Bronze C5210R-EH Thickness=0.35mm
 Pins: Brass C2680R-H Thickness=0.25mm
 Shield: SUS S304-1/2H Thickness=0.2mm
 Contact plating: Gold 6 micro-inches min. In contact area.
4. Wave solder tip temperature: 265°C Max, 5 Sec Max

X:X	±0.30	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED	
X:XX	±0.20	CHKD:	Title: RJ45 10/100/1000BASE-TX JACK/ Dual USB Combo	
X:XXX	±0.10	DR: TOM		
ANGLES	±1°	UNIT: mm	PART NO.: LPJU5601BHNL	
	SCALE: 2/1	SHEET: 2/2	REV: A	DWG NO.: LP11081704